



*Industrial Computing Platform Partner*

# **HSB-835A A0.2**

## **Temperature cycle Test Report**

**Report NO: 04I020012**

Issued by: Rex Chang / 12/07/2004  
Engineer

Reviewed by: Wenyuan Yang / 12/07/2004  
Manager

HSB-835A A0.2

Test Date: 12-03~07-2004

Test Product: HSB-835A (PCB Rev: A0.2 BIOS Rev: 0.2)

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

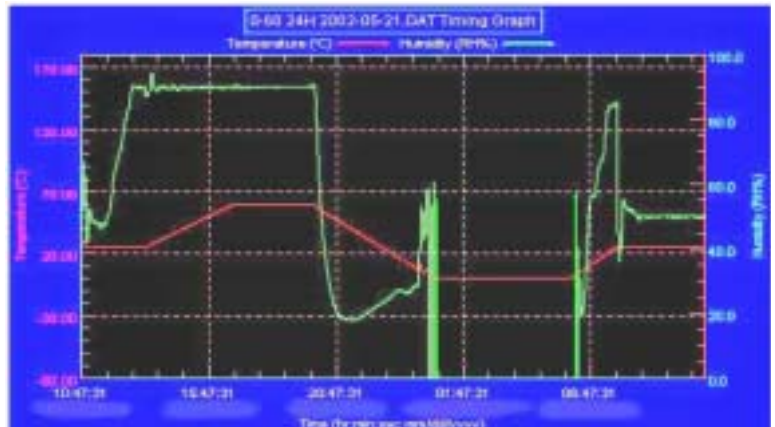
**Test Standard:** Reference IEC 68-2-30 Testing procedures  
 Test DB: Damp Heat Test  
 Reference IEC 68-2-61 Testing procedures  
 Test Z/ABD: Climatic Sequence Test

**Test Equipment:**  
 Programmable Temperature & Humidity Chamber  
 K.SON. INS. TECH. CORP.  
 Model: THS-A4C-100  
 Date of Calibration: 05/24/04  
 Serial Number: 3188

**Temperature & Humidity Power On/Off Test:  
 Testing Specification:**

Step	Temperature ( )	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	25	90	01:00
4	25	90	00:30
5	60	90	03:30
6	60	90	03:00
7	0	0	04:50
8	0	0	05:23
9	25	50	01:47
10	25	50	03:00

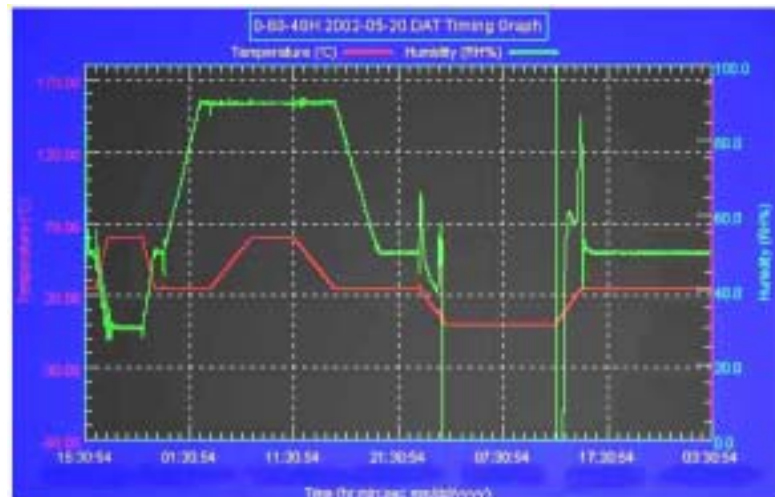
**Test Curve:**



**Temperature & Humidity Cycle Test:  
 Testing Specification**

Step	Temperature ( )	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	60	30	01:10
4	60	30	03:20
5	25	50	01:10
6	25	50	00:50
7	25	90	03:30
8	25	90	01:00
9	60	90	03:53
10	60	90	04:07
11	25	90	03:53
12	25	50	04:07
13	25	50	03:30
14	25	50	00:30
15	0	0	02:30
16	0	0	10:30
17	25	50	02:30
18	25	50	00:30

**Test Curve:**



## Sample Configuration & Quantity Under Test:

1. CPU: Intel Pentium 4 / 2A GHz CPU
2. Memory: 256MB Kingston D3208DL1T-6 (DDR-333) \* 1  
256MB SAMSUNG K4H280838B-TCB0 (DDR-266) \* 1
3. Chipset: Intel 865G/PE + Intel 82801EB/ER (ICH5/ICH5R)
4. VGA: Integrated on Intel 865G
5. LAN: Intel 82562EZ
6. CFD: PQI 32MB
7. HDD: Maxtor DiamondMax Plus 9 80GB
8. Power Supply: Seventeam ST-300BLV
9. Backplane: BP-214SA-P6I6 A1.1
10. Test Software: Windows 2000 / Run HCT 9.5
11. Cooler:



**Test Result :**

**Passed.**